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NEXX Systems Receives Repeat Order for Multi-platform Products from Unisem Advanced Technologies

Billerica, MA – June 29, 2010 – NEXX Systems – a leading provider of advanced wafer-level chip scale packaging equipment, headquartered in the Boston area – today announced a repeat, multi-product order for an Apollo physical vapor deposition system and Stratus electrochemical deposition system to Unisem Advanced Technologies (UAT), a wafer bumping facility in Malaysia. Both systems will be used for WLCSP and bumping in support of Unisem's industry leadership in flip chip packaging. The Stratus, already installed in UAT, was in production in less than two weeks from its delivery date.

The Unisem/NEXX partnership has been a strong success: NEXX Systems, an established multi-platform provider to UAT, provided accelerated system shipment and commissioning, as well as partnered with UAT to provide superior unit processes and low cost of ownership. NEXX Systems is committed to enabling its partners to consistently deliver technology leadership and cost effective production of wafer level packaging solutions.

About UAT: Unisem Advanced Technologies (UAT), a joint venture between Unisem (M) Berhad, Advanpack Solutions Pte. Ltd. and FlipChip International, located in Ipoh, Malaysia, is one of the first independent wafer bumping service providers in Malaysia.

Unisem is a global provider of semiconductor assembly and test services for many of the most successful electronics companies. Unisem offers an integrated suite of packaging and test services, a wide range of leadframe and substrate IC packaging, and high-end RF and mix-signal test services. Additional information can be found at: <http://www.unisemgroup.com>.

About Stratus/Apollo Product Families: Stratus provides industry-leading yield at what we believe is the lowest CoO for pattern plating and TSV applications. NEXX Systems' AquaTorr™, an advanced prewet system, enables high aspect ratio, void-free copper fill for TSVs. Innovative ShearPlate™ technology provides exceptional process with excellent across wafer uniformity and alloy composition.

The Apollo advanced sputter deposition system incorporates multi-wafer processing commonly used in cluster tools while avoiding the disadvantages of central handling. The Apollo, specifically designed for wafer level packaging offers faster, more economical PVD processing.

About NEXX: NEXX Systems brings exceptional technical expertise to the flip chip and advanced packaging markets. The Stratus and Apollo product families provide the most efficient, yet affordable, systems of their kind. Additional information can be found at: www.nexxsystems.com.